# UTHM
Universiti Tun Hussein Onn Malaysia

# UNIVERSITI TUN HUSSEIN ONN MALAYSIA

## FINAL EXAMINATION
## (OTHER SUMMATIVE ASSESSMENT)
## SEMESTER II
## SESSION 2019/2020

| | | |
|---|---|---|
| COURSE NAME | : | IC PACKAGING |
| COURSE CODE | : | BED 41103 |
| PROGRAMME CODE | : | BEJ |
| EXAMINATION DATE | : | JULY 2020 |
| DURATION | : | 5 HOURS |
| INSTRUCTION | : | ANSWER **ALL** QUESTIONS **OPEN BOOK EXAMINATION** |

**TERBUKA**

THIS QUESTION PAPER CONSISTS OF **TWO (2)** PAGES

BED 41103

**Q1** (a) Microsystems and the technologies constitute are building blocks of information technology. These systems require a set of fundamental technologies that include not only microelectronics but also photonics, Micro-Electromechanical System (MEMS), Radio Frequency (RF) and wireless. For these functions to be integrated into systems, it has to be designed, fabricated, tested, cooled and reliability assured. In other words, they have to be system-packaged.

Find one real integrated circuits using BGA package. Identify information about your ICs prior to report:

The whole process of IC package
Manufacturer
Part number
Function
Datasheet
Date of manufacturer

**Please submit your report within 5 hours from this exam start.**

( 100 Marks)

-END OF QUESTIONS -